

ABSTRACT OF THE DISCLOSURE

An integrated circuit package separator for separating integrated circuit packages from a board includes a base, a support over the base, and a pair of pneumatic actuators including first and second lift members laterally spaced from the base and beneath respective ends of a pair of opposing ends of the support. The first and second lift members are configured to vertically displace the support and lift the support off the base by contacting the support. Individual actuators of the pair include release valves configured to equilibrate a back-pressure of the individual actuators to ambient during lifting of the support. The separator includes a cutting mechanism configured to cut the board while the board is over the upper surface of the support to separate the integrated circuit packages from one another.